

Radiation Hardened Octal Three-State Transparent Latch

January 1996

Features

- Devices QML Qualified in Accordance with MIL-PRF-38535
- Detailed Electrical and Screening Requirements are Contained in SMD# 5962-96724 and Intersil's QM Plan
- 1.25 Micron Radiation Hardened SOS CMOS
- Total Dose >300K RAD (Si)
- Single Event Upset (SEU) Immunity: <math> < 1 \times 10^{-10}</math> Errors/Bit/Day (Typ)
- SEU LET Threshold >100 MEV-cm²/mg
- Dose Rate Upset >10¹¹ RAD (Si)/s, 20ns Pulse
- Dose Rate Survivability >10¹² RAD (Si)/s, 20ns Pulse
- Latch-Up Free Under Any Conditions
- Military Temperature Range -55°C to +125°C
- Significant Power Reduction Compared to ALSTTL Logic
- DC Operating Voltage Range 4.5V to 5.5V
- Input Logic Levels
 - VIL = 30% of VCC Max
 - VIH = 70% of VCC Min
- Input Current ≤ 1μA at VOL, VOH
- Fast Propagation Delay 17ns (Max), 12ns (Typ)

Description

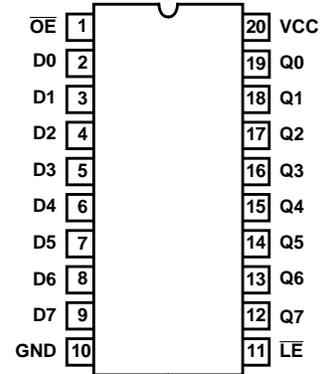
The Intersil ACS573MS is a Radiation Hardened Octal Transparent Latch with an active low output enable. The outputs are transparent to the inputs when the latch enable (LE) is High. When the latch goes low the data is latched. The output enable controls the three-state outputs. When the output enable pins (\overline{OE}) are high the output is in a high impedance state. The latch operation is independent of the state of output enable.

The ACS573MS utilizes advanced CMOS/SOS technology to achieve high-speed operation. This device is a member of a radiation hardened, high-speed, CMOS/SOS Logic family.

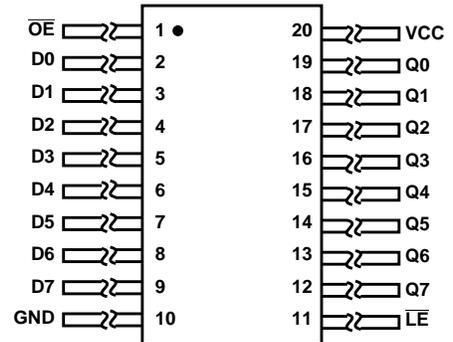
The ACS573MS is supplied in a 20 lead Ceramic Flatpack (K suffix) or a

Pinouts

20 LEAD CERAMIC DUAL-IN-LINE
MIL-STD-1835 DESIGNATOR,
CDIP2-T20, LEAD FINISH C
TOP VIEW



20 LEAD CERAMIC FLATPACK
MIL-STD-1835 DESIGNATOR,
CDFP4-F20, LEAD FINISH C
TOP VIEW



Ordering Information

PART NUMBER	TEMPERATURE RANGE	SCREENING LEVEL	PACKAGE
5962F9672401VRC	-55°C to +125°C	MIL-PRF-38535 Class V	20 Lead SBDIP
5962F9672401VXC	-55°C to +125°C	MIL-PRF-38535 Class V	20 Lead Ceramic Flatpack
ACS573D/Sample	25°C	Sample	20 Lead SBDIP
ACS573K/Sample	25°C	Sample	20 Lead Ceramic Flatpack
ACS573HMSR	25°C	Die	Die

ACS573MS

Die Characteristics

DIE DIMENSIONS:

102 mils x 102 mils
2,600mm x 2,600mm

METALLIZATION:

Type: AlSi
Metal 1 Thickness: $7.125\text{k}\text{\AA} \pm 1.125\text{k}\text{\AA}$
Metal 2 Thickness: $9\text{k}\text{\AA} \pm 1\text{k}\text{\AA}$

GLASSIVATION:

Type: SiO_2
Thickness: $8\text{k}\text{\AA} \pm 1\text{k}\text{\AA}$

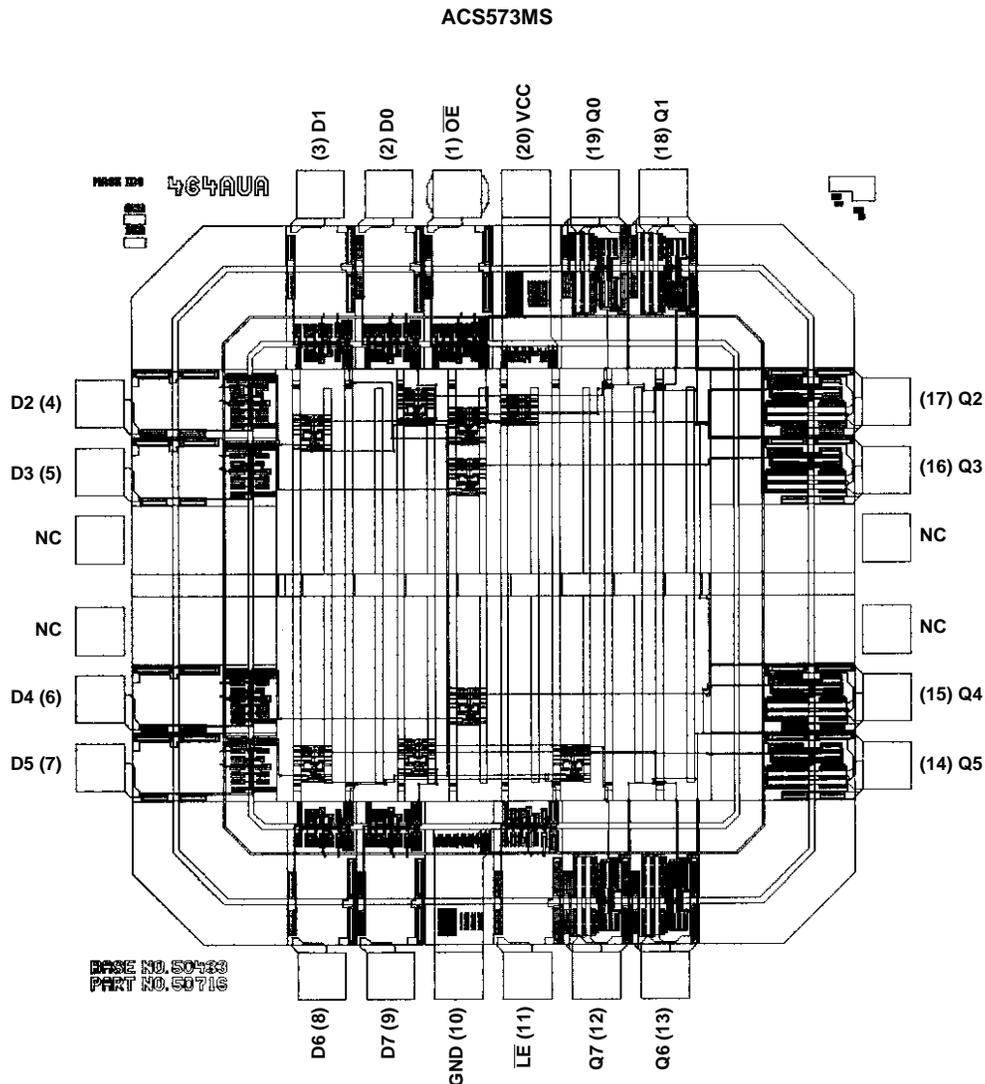
WORST CASE CURRENT DENSITY:

$< 2.0 \times 10^5 \text{ A/cm}^2$

BOND PAD SIZE:

$> 4.3 \text{ mils} \times 4.3 \text{ mils}$
 $> 110\mu\text{m} \times 110\mu\text{m}$

Metallization Mask Layout



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